



# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

| APPLICATION NO.                       | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO.     | CONFIRMATION NO. |
|---------------------------------------|-------------|----------------------|-------------------------|------------------|
| 09/731,385                            | 12/06/2000  | Myeong-cheol Kim     | SAM-164                 | 8322             |
| 7590 12/09/2003                       |             |                      | EXAMINER                |                  |
| Mills & Onello LLP                    |             |                      | NADAV, ORI              |                  |
| Eleven Beacon Street Boston, MA 02108 |             |                      | ART UNIT                | PAPER NUMBER     |
|                                       |             |                      | 2811                    |                  |
|                                       |             |                      | DATE MAILED: 12/09/2003 |                  |

Please find below and/or attached an Office communication concerning this application or proceeding.

|   | Application No.   | Applicant(s)  |  |  |  |
|---|---|---|--|--|--|
|   | 09/731,385  | KIM ET AL.  |  |  |  |
| Office Action Summary   | Examiner  | Art Unit  |  |  |  |
|   | ori nadav   | 2811  |  |  |  |
| The MAILING DATE of this communication appears on the cover sheet with the correspondence address<br>Period for Reply   |   |   |  |  |  |
| A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.  - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.  - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).  - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).  Status |   |   |  |  |  |
| 1) Responsive to communication(s) filed on 29 S   | September 2003 .  |   |  |  |  |
| 2a) ☐ This action is FINAL. 2b) ☑ Th  | ) This action is <b>FINAL</b> . 2b) This action is non-final. |   |  |  |  |
| 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.  Disposition of Claims   |   |   |  |  |  |
| 4)⊠ Claim(s) <u>1-11 and 14-20</u> is/are pending in the application.   |   |   |  |  |  |
| 4a) Of the above claim(s) <u>16-20</u> is/are withdrawn from consideration.   |   |   |  |  |  |
| 5) Claim(s) is/are allowed.   |   |   |  |  |  |
| 6)⊠ Claim(s) <u>1-11,14 and 15</u> is/are rejected.   |   |   |  |  |  |
| 7) Claim(s) is/are objected to.   |   |   |  |  |  |
| 8) Claim(s) are subject to restriction and/or election requirement.   |   |   |  |  |  |
| Application Papers  |   |   |  |  |  |
| 9) ☐ The specification is objected to by the Examiner.  |   |   |  |  |  |
| 10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.  |   |   |  |  |  |
| Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).   |   |   |  |  |  |
| 11) The proposed drawing correction filed on is: a) □ approved b) □ disapproved by the Examiner.  |   |   |  |  |  |
| If approved, corrected drawings are required in reply to this Office action.  |   |   |  |  |  |
| 12) ☐ The oath or declaration is objected to by the Examiner.   |   |   |  |  |  |
| Priority under 35 U.S.C. §§ 119 and 120   |   |   |  |  |  |
| 13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).   |   |   |  |  |  |
| a) ☐ All b) ☐ Some * c) ☐ None of:  |   |   |  |  |  |
| 1. Certified copies of the priority documents have been received.   |   |   |  |  |  |
| 2. Certified copies of the priority documents have been received in Application No  |   |   |  |  |  |
| <ul> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>   |   |   |  |  |  |
| 14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).  |   |   |  |  |  |
| a) ☐ The translation of the foreign language provisional application has been received.  15)☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.  |   |   |  |  |  |
| Attachment(s)   |   |   |  |  |  |
| 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)   | 5) Notice of Informal   | r (PTO-413) Paper No(s)<br>Patent Application (PTO-152) |  |  |  |
| S. Patent and Trademark Office PTOL = 326 (Rev. 04-01) Office A   | ction Summary   | Part of Paper No. 20                                    |  |  |  |

Art Unit: 2811

#### **DETAILED ACTION**

#### Claim Rejections - 35 USC § 112

The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

Claims 1-11 and 14-15 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. The specification describes a second conductive layer formed between adjacent conductive patterns and a first insulation layer extending in the gap between the conductive patterns and the second conductive layer. There is no support in the specification for the claimed limitation of a first insulation layer being located throughout the entire distance between adjacent conductive patterns, as recited in claim 1, since the first insulation layer is not present where the second conductive layer is located.

Art Unit: 2811

#### Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

1. Claims 1-8, 10 and 15 are rejected under 35 U.S.C. 102(e) as being anticipated by Nguyen (6,472,261).

Regarding claims 1, 4-7 and 15, Nguyen teaches in figure 6 and related text a semiconductor device having a self-aligned contact, the semiconductor device comprising: a plurality of conductive patterns formed to be adjacent to one an other by sequentially stacking and patterning a first conductive layer 14 and a mask layer 18 on a particular underlying layer 10; a first insulation layer 22 filling a gap between adjacent conductive patterns the first insulation layer being formed of a first insulating material and being formed laterally adjacent to and not underneath the conductive patterns,

a second insulation layer 28 having a spacer shape, the second insulation layer formed at the sides of each conductive pattern and over the first insulation layer; the second insulation layer being formed of a second insulating material different from the first insulating material, and

a second conductive layer 42 filling a contact hole which is self-aligned with respect to the second insulation layer between adjacent conductive patterns, the

Art Unit: 2811

contact hole passing through the first insulation layer, the first insulation layer extending between adjacent conductive patterns and between the second conductive layer and the conductive patterns and having a planar top surface throughout the entire distance between adjacent conductive patterns.

Regarding the claimed limitation of a first insulation layer having a planar top surface, although Nguyen teaches in figure 6 a first insulation layer having an L shape, the top surface of the first insulation layer has a planar top surface since it has no curvature in its top surface.

Regarding claim 2, Nguyen teaches in figure 6 a top of the first insulation layer 22 being lower than the top of the first conductive layer 14 of each conductive layer pattern.

Regarding claims 3, Nguyen teaches in figure 6 and related text the top of the first insulation layer 22 (the first insulation layer 22 is taken as the horizontal layer 22 and the vertical layer adjacent to the first conductive layer 14) is higher than the top of the first conductive layer 14 of each conductive layer pattern.

Regarding claim 4-7, Nguyen teaches in figure 6 an etching rate of the first insulation layer is larger than that of the second insulation layer, the dielectric constant of the first insulation layer is smaller than that of the second insulation layer, wherein the first insulation layer is formed of a silicon oxide layer and the second insulation layer is formed of a silicon nitride layer.

Art Unit: 2811

Regarding claim 8, Nguyen teaches in figure 6 a third insulation layer provided between the first insulation layer and the sides of each conductive layer pattern and between the second insulation layer and the side of the conductive layer pattern.

Regarding claim 10, Nguyen teaches in figure 6 a fourth insulation layer 34 provided on the surface of the underlying layer except for a portion contacting the second conductive layer 42 and on the surfaces of the conductive layer patterns.

Regarding claim 15, Nguyen teaches in figure 6 the first conductive layer of each conductive layer pattern is a gate electrode, and the contact contacts the surface of a semiconductor substrate.

### Claim Rejections - 35 USC ' 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which the subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claim 11 is rejected under 35 U.S.C. 103(a) as being unpatentable over Nguyen.

Regarding claim 11, Nguyen teaches substantially the entire claimed structure, as applied to dependent claim 10 and independent claim 1 above, except stating that the

Page 6

Application/Control Number: 09/731,385

Art Unit: 2811

third and fourth insulation layers are formed at a thickness of 50-200 A. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use third and fourth insulation layers at a thickness of 50-200 A in Nguyen's device, in order to provide adequate insulation to the device and because it is well within the skills of an artisan to optimize the performance of the device by forming the third and fourth insulation layers at the required thickness.

4. Claim 9 is rejected under 35 U.S.C. 103(a) as being unpatentable over Nguyen.

Regarding claim 9, Nguyen teach substantially the entire claimed structure, as applied to dependent claim 8 and independent claim 1 above, except stating that the third and fourth insulation layers are formed at a thickness of 50-200 A. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use third and fourth insulation layers at a thickness of 50-200 A in Nguyen's device, in order to provide adequate insulation to the device and because it is well within the skills of an artisan to optimize the performance of the device by forming the third and fourth insulation layers at the required thickness.

5. Claim 14 is rejected under 35 U.S.C. 103(a) as being unpatentable over Nguyen in view of Huang (5,899,722).

Nguyen teaches substantially the entire claimed structure, as applied to claim 1 above, except using the first conductive layer of each conductive layer pattern as a bit line, and

Art Unit: 2811

the second conductive layer to connect a storage electrode of a semiconductor capacitor to a semiconductor substrate.

Huang teaches that a self aligned contact structure, similar to that disclosed by Chang et al., can be used in a DRAM. A DRAM comprises a first conductive layer being a bit line, and a second conductive layer serves to connect a storage electrode of a semiconductor capacitor to a semiconductor substrate. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use Nguyen's device in a DRAM device in order to use the device in a specific application which requires a DRAM device. Note that a recitation of the intended use of the claimed invention must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim. See *In re Casey*, 152 USPQ 235 (CCPA 1967) and *In re Otto*, 136 USPQ 458, 459 (CCPA 1963).

## Response to Arguments

6. Applicant's arguments with respect to claims 1-11 and 14-15 have been considered but are most in view of the new ground(s) of rejection.

Papers related to this application may be submitted to Technology center (TC) 2800 by facsimile transmission. Papers should be faxed to TC 2800 via the TC

Art Unit: 2811

2800 Fax center located in Crystal Plaza 4, room 4-C23. The faxing of such papers must conform with the notice published in the Official Gazette, 1096 OG 30 (November 15, 1989). The Group 2811 Fax Center number is (703) 308-7722 and 308-7724. The Group 2811 Fax Center is to be used only for papers related to Group 2811 applications.

Any inquiry concerning this communication or any earlier communication from the Examiner should be directed to *Examiner Nadav* whose telephone number is **(703) 308-8138**. The Examiner is in the Office generally between the hours of 7 AM to 4 PM (Eastern Standard Time) Monday through Friday.

Any inquiry of a general nature or relating to the status of this application should be directed to the **Technology Center Receptionists** whose telephone number is **308-0956** 

O.N. December 8, 2003 ORI: NADAV
PATENT EXAMINER
TECHNOLOGY CENTER 2800

On Nat